

SONY

CXP84332M/84340M

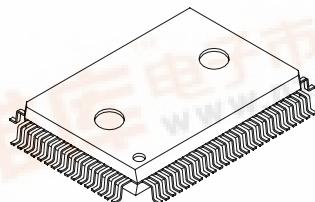
CMOS 8-bit Single Chip Microcomputer

Description

CXP84332M/84340M is a CMOS 8-bit single chip microcomputer integrating on a single chip an A/D converter, serial interface, timer/counter, time base timer, capture timer/counter, remote control reception circuit, PWM output, and 32kHz timer/counter besides the basic configurations of 8-bit CPU, ROM, RAM, and I/O port.

The CXP84332M/84340M also provides a sleep/stop function that enables lower power consumption.

80 pin QFP (Plastic)

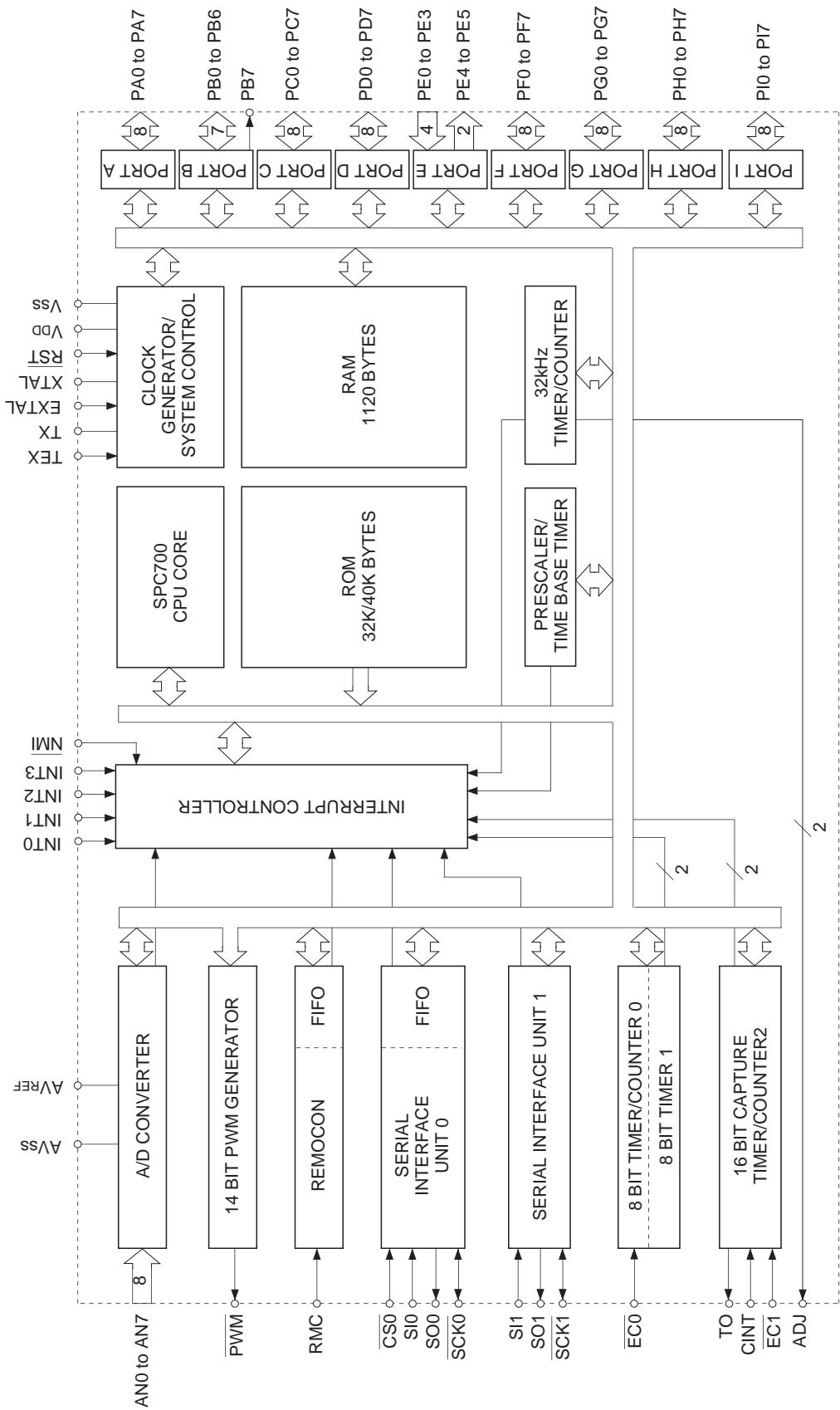


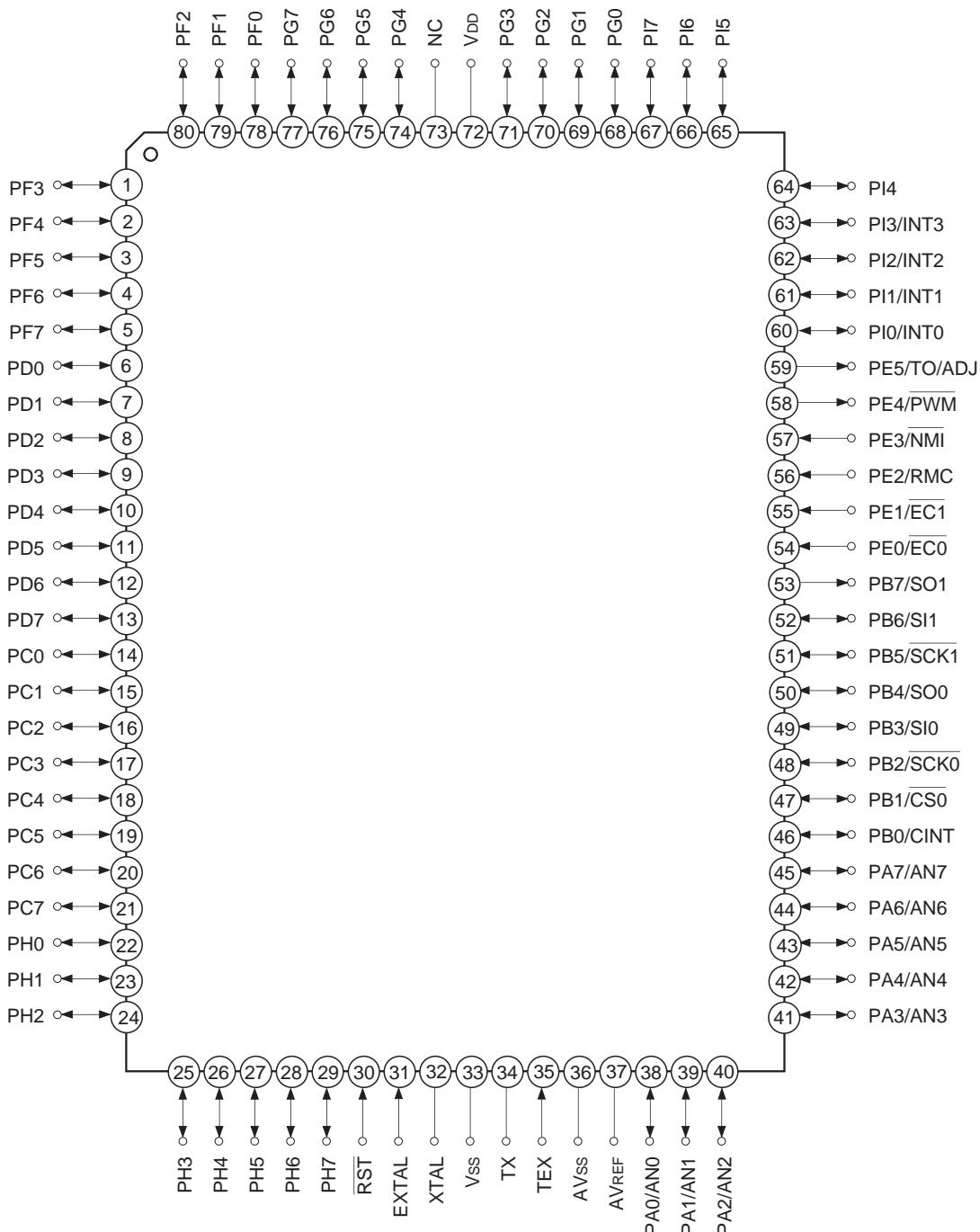
Features

- Wide-range instruction system (213 instructions) to cover various types of data
 - 16-bit arithmetic/multiplication and division/boolean bit operation instructions
- Minimum instruction cycle
 - 200ns at 20MHz operation
 - 122 μ s at 32kHz operation
- Incorporated ROM capacity
 - 32K bytes (CXP84332M)
 - 40K bytes (CXP84340M)
 - 1120 bytes
- Incorporated RAM capacity
- Peripheral functions
 - A/D converter
 - 8 bits, 8 channels, successive approximation method
(Conversion time of 16 μ s/20MHz)
 - Serial interface
 - 8-bit, 8-stage FIFO incorporated
(Auto transfer for 1 to 8 bytes), 1 channel
 - 8-bit clock synchronization, 1 channel
 - Timers
 - 8-bit timer
 - 8-bit timer/counter
 - 19-bit time base timer
 - 16-bit capture timer/counter
 - 32kHz timer/counter
 - Remote control reception circuit
 - PWM output
- Interruption
- Standby mode
- Package
 - 80-pin plastic QFP
 - CXP84300 80-pin ceramic QFP
- Piggyback/evaluation chip

Structure

Silicon gate CMOS IC

Block Diagram

Pin Assignment (Top View)

Pin Description

Pin code	I/O	Functions	
PA0/AN0 to PA7/AN7	I/O/Analog input	(Port A) 8-bit I/O port. I/O can be set in a unit of single bits. Incorporation of the pull-up resistance can be set through the software in a unit of 4 bits. (8 pins)	Analog inputs to A/D converter. (8 pins)
PB0/CINT	I/O/Input	(Port B)	External capture input to 16-bit timer/counter.
PB1/ <u>CS0</u>	I/O/Input		Chip select input for serial interface (CH0).
PB2/SCK0	I/O/I/O		Serial clock I/O (CH0).
PB3/SI0	I/O/Input		Serial data input (CH0).
PB4/SO0	I/O/Output		Serial data output (CH0).
PB5/ <u>SCK1</u>	I/O/I/O		Serial clock I/O (CH1).
PB6/SI1	I/O/Input		Serial data input (CH1).
PB7/SO1	Output/Output	(8 pins)	Serial data output (CH1).
PC0 to PC7	I/O	(Port C) 8-bit I/O port. I/O can be set in a unit of single bits. Capable of driving 12mA sync current. Incorporation of pull-up resistor can be set through the software in a unit of 4 bits. (8 pins)	
PD0 to PD7	I/O	(Port D) 8-bit I/O port. I/O can be set in a unit of single bits. Incorporation of pull-up resistor can be set through the software in a unit of 4 bits. (8 pins)	
PE0/ <u>EC0</u>	Input/Input	(Port E) 6-bit port. Lower 4 bits are for inputs; upper 2 bits are for outputs. (6 pins)	External event inputs for timer/counter. (2 pins)
PE1/ <u>EC1</u>	Input/Input		Remote control reception circuit input.
PE2/RMC	Input/Input		Non-maskable interruption request input.
PE3/ <u>NMI</u>	Input/Input		14-bit PWM output.
PE4/PWM	Output/Output		Rectangular wave output for 16-bit timer/counter and output for 32kHz oscillation frequency demultiplication.
PE5/TO/ADJ	Output/Output/ Output		
PF0 to PF7	I/O	(Port F) 8-bit I/O port. I/O can be set in a unit of single bits. Incorporation of pull-up resistor can be set through the software in a unit of 4 bits. (8 pins)	

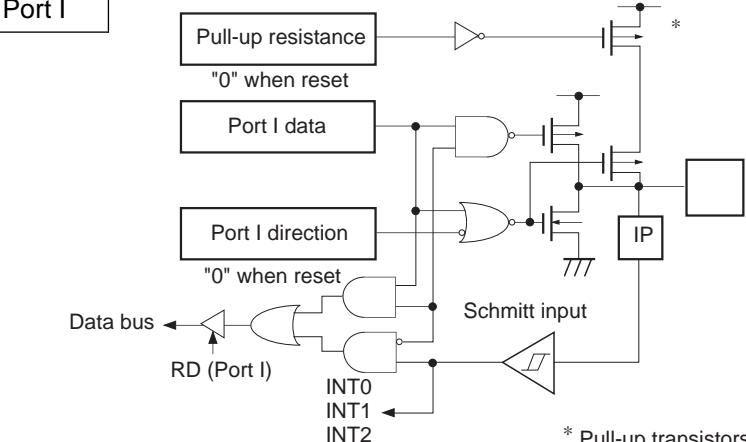
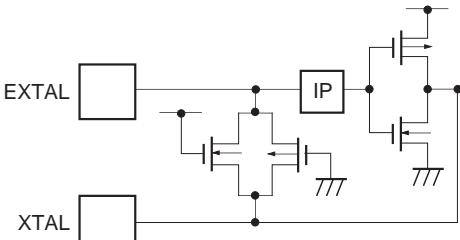
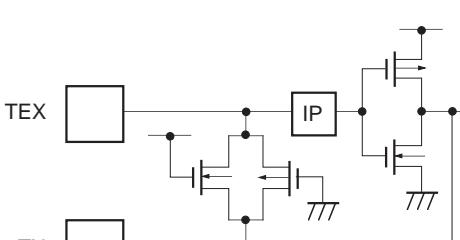
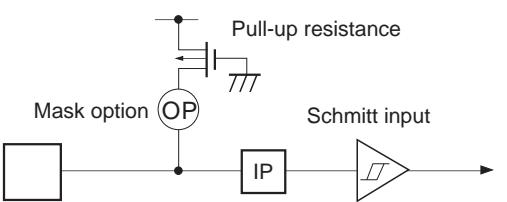
Pin code	I/O	Functions	
PG0 to PG7	I/O	(Port G) 8-bit I/O port. I/O can be set in a unit of single bits. Incorporation of pull-up resistor can be set through the software in a unit of 4 bits. (8 pins)	
PH0 to PH7	I/O	(Port H) 8-bit I/O port. I/O can be set in a unit of single bits. Incorporation of pull-up resistor can be set through the software in a unit of 4 bits. (8 pins)	
PI0/INT0 to PI3/INT3	I/O/Input	(Port I) 8-bit I/O ports. I/O can be set in a unit of single bits. Incorporation of pull-up resistor can be set through the software in a unit of 4 bits.	External interruption request inputs. (4 pins)
PI4 to PI7	I/O	(8 pins)	
EXTAL	Input	Crystal connectors for system clock oscillation. When the clock is supplied externally, input to EXTAL; opposite phase clock should be input to XTAL.	
XTAL	Output		
TEX	Input	Crystal connectors for 32kHz timer/counter clock oscillation circuit.	
TX	Output	For usage as event counter, input to TEX, and open TX.	
RST	Input	Low-level active, system reset.	
NC		NC. Under normal operating conditions, connect to V _{DD} .	
AV _{REF}	Input	Reference voltage input for A/D converter.	
AV _{ss}		A/D converter GND.	
V _{DD}		Vcc supply.	
V _{ss}		GND	

I/O Circuit Format for Pins

Pin	Circuit format	When reset
PA0/AN0 to PA7/AN7 8 pins	<p>Port A</p> <p>Pull-up resistance "0" when reset</p> <p>Port A data</p> <p>Port A direction "0" when reset</p> <p>Data bus</p> <p>RD (Port A)</p> <p>Port A input selection "0" when reset</p> <p>Input multiplexer</p> <p>A/D converter</p> <p>IP Input protection circuit</p> <p>* Pull-up transistors approx. 10kΩ</p>	Hi-Z
PB0/CINT PB1/CS0 PB3/SI0 PB6/SI1 4 pins	<p>Port B</p> <p>Pull-up resistance "0" when reset</p> <p>Port B data</p> <p>Port B direction "0" when reset</p> <p>Data bus</p> <p>RD (Port B)</p> <p>CINT CS0 SI0 SI1</p> <p>Schmitt input</p> <p>* Pull-up transistors approx. 10kΩ</p>	Hi-Z
PB2/SCK0 PB5/SCK1 2 pins	<p>Port B</p> <p>Pull-up resistance "0" when reset</p> <p>SCK OUT Output enable</p> <p>Port B output selection "0" when reset</p> <p>Port B data</p> <p>Port B direction "0" when reset</p> <p>Data bus</p> <p>RD (Port B)</p> <p>SCK in</p> <p>Schmitt input</p> <p>* Pull-up transistors approx. 10kΩ</p>	Hi-Z

Pin	Circuit format	When reset
PB4/SO0 1 pin	<p>Port B</p> <p>Pull-up resistance "0" when reset</p> <p>SO Output enable</p> <p>Port B output selection "0" when reset</p> <p>Port B data</p> <p>Port B direction "0" when reset</p> <p>Data bus</p> <p>RD (Port B)</p> <p>* Pull-up transistors approx. 10kΩ</p>	Hi-Z
PB7/SO1 1 pin	<p>Port B</p> <p>Internal reset signal</p> <p>SO Output enable</p> <p>Port B output selection "1" when reset</p> <p>Port B data</p> <p>Data bus</p> <p>RD (Port B)</p> <p>* Pull-up transistors approx. 200kΩ</p>	High level with approx. 200kΩ resistor when reset
PC0 to PC7 8 pins	<p>Port C</p> <p>Pull-up resistance "0" when reset</p> <p>Port C data</p> <p>Port C direction "0" when reset</p> <p>Data bus</p> <p>RD (Port C)</p> <p>*1 Large current 12mA</p> <p>*2 Pull-up transistors approx. 10kΩ</p>	Hi-Z
PE0/EC0 PE1/EC1 PE2/RMC PE3/NMI 4 pins	<p>Port E</p> <p>Schmitt input</p> <p>IP</p> <p>EC0 EC1 RMC/NMI</p> <p>Data bus</p> <p>RD (Port E)</p>	Hi-Z

Pin	Circuit format	When reset
PE4/PWM 1 pin	<p>Port E</p> <p>The circuit shows Port E output selection logic. It takes three inputs: PWM, Port E output selection ("0" when reset), and Port E data ("1" when reset). The PWM signal is inverted and combined with the output selection signal via an AND gate. This is followed by another AND gate with Port E data as one input. The outputs of these two AND gates are combined via an OR gate. The output of this OR gate is connected to a driver stage consisting of a PMOS transistor and an NMOS transistor. A third NMOS transistor is connected between the source of the PMOS and ground. The drain of the PMOS is connected to the output pin. The drain of the NMOS is connected to the source of the PMOS. The source of the NMOS is connected to ground. The gate of the PMOS is connected to the output of the OR gate. The gate of the NMOS is connected to the drain of the PMOS.</p>	High level
PE5/TO/ADJ 1 pin	<p>Port E</p> <p>The circuit shows Port E output selection logic. It takes four inputs: TO, ADJ16K, ADJ2K, and Port E output selection ("00" when reset). The TO signal is inverted and combined with the ADJ16K and ADJ2K signals via an AND gate. This is followed by another AND gate with Port E output selection ("00" when reset) as one input. The outputs of these two AND gates are combined via an OR gate. The output of this OR gate is connected to a driver stage consisting of a PMOS transistor and an NMOS transistor. A third NMOS transistor is connected between the source of the PMOS and ground. The drain of the PMOS is connected to the output pin. The drain of the NMOS is connected to the source of the PMOS. The source of the NMOS is connected to ground. The gate of the PMOS is connected to the output of the OR gate. The gate of the NMOS is connected to the drain of the PMOS.</p> <p>* ADJ signals are frequency dividing outputs for 32kHz oscillation frequency adjustment ADJ2K provides usage as buzzer output.</p>	High level
PD0 to PD7 PF0 to PF7 PG0 to PG7 PH0 to PH7 PI4 to PI7 36 pins	<p>Port D Port F Port G Port H Port I</p> <p>The circuit shows Port D output selection logic. It takes five inputs: Pull-up resistance ("0" when reset), Ports D, F, G, H, I data, and Ports D, F, G, H, I direction ("0" when reset). The Pull-up resistance signal is inverted and combined with the Ports D, F, G, H, I data signal via an AND gate. This is followed by another AND gate with Ports D, F, G, H, I direction ("0" when reset) as one input. The outputs of these two AND gates are combined via an OR gate. The output of this OR gate is connected to a driver stage consisting of a PMOS transistor and an NMOS transistor. A third NMOS transistor is connected between the source of the PMOS and ground. The drain of the PMOS is connected to the output pin. The drain of the NMOS is connected to the source of the PMOS. The source of the NMOS is connected to ground. The gate of the PMOS is connected to the output of the OR gate. The gate of the NMOS is connected to the drain of the PMOS.</p> <p>* Pull-up transistors approx. 10kΩ</p>	Hi-Z

Pin	Circuit format	When reset
PIO/INT0 to PI3/INT3 4 pins	 <p>Port I</p> <p>Pull-up resistance "0" when reset</p> <p>Port I data</p> <p>Port I direction "0" when reset</p> <p>Data bus RD (Port I)</p> <p>INT0 INT1 INT2 INT3</p> <p>* Pull-up transistors approx. 10kΩ</p>	Hi-Z
EXTAL XTAL 2 pins	 <ul style="list-style-type: none"> Diagram shows circuit composition during oscillation. Feedback resistor is removed during stop. 	Oscillation
TEX TX 2 pins	 <ul style="list-style-type: none"> Diagram shows circuit composition during oscillation. When the operation of the oscillation circuit is stopped by the software, the feedback resistor is removed, and TEX and TX become "Low" level and "High" level respectively. 	Oscillation
RST 1 pin	 <p>Pull-up resistance</p> <p>Mask option OP</p> <p>Schmitt input</p>	Low level

Absolute Maximum Ratings

(Vss = 0V reference)

Item	Symbol	Ratings	Unit	Remarks
Supply voltage	VDD	-0.3 to +7.0	V	
	AVss	-0.3 to +0.3	V	
Input voltage	VIN	-0.3 to +7.0 ^{*1}	V	
Output voltage	VOUT	-0.3 to +7.0 ^{*1}	V	
High level output current	I _{OH}	-5	mA	Output per pin
High level total output current	ΣI_{OH}	-50	mA	Total for all output pins
Low level output current	I _{OL}	15	mA	Value per pin, excluding large current outputs
	I _{OLC}	20	mA	Value per pin ^{*2} for large current outputs
Low level total output current	ΣI_{OL}	100	mA	Total for all output pins
Operating temperature	Topr	-20 to +75	°C	
Storage temperature	Tstg	-55 to +150	°C	
Allowable power dissipation	P _D	600	mW	

^{*1) VIN and VOUT must not exceed VDD + 0.3V.}^{*2) The large current drive transistor is the N-ch transistor of Port C (PC).}

Note) Usage exceeding absolute maximum ratings may permanently impair the LSI. Normal operation should be conducted under the recommended operating conditions. Exceeding these conditions may adversely affect the reliability of the LSI.

Recommended Operating Conditions

(Vss = 0V reference)

Item	Symbol	Min.	Max.	Unit	Remarks
Supply voltage	VDD	4.5	5.5	V	Guaranteed operation range for high speed mode ^{*1}
		3.5	5.5		Guaranteed operation range for low speed mode ^{*1}
		2.7	5.5		Guaranteed operation range with TEX clock
		2.5	5.5		Guaranteed data hold range during STOP
High level input voltage	V _{IH}	0.7V _{DD}	V _{DD}	V	^{*2}
	V _{IHS}	0.8V _{DD}	V _{DD}	V	Hysteresis input ^{*3}
	V _{IHEX}	V _{DD} - 0.4	V _{DD} + 0.3	V	EXTAL ^{*4}
Low level input voltage	V _{IL}	0	0.3V _{DD}	V	^{*2}
	V _{ILS}	0	0.2V _{DD}	V	Hysteresis input ^{*3}
	V _{ILEX}	-0.3	0.4	V	EXTAL ^{*4}
Operating temperature	Topr	-20	+75	°C	

^{*1) High speed mode is 1/2 frequency dividing clock selection; low-speed mode is 1/16 frequency dividing clock selection.}^{*2) Value for each pin of normal input ports (PA, PB3, PB4, PB6, PC, PD, PF to PH, PI4 to PI7).}^{*3) Value of the following pins: \overline{RST} , CINT, $\overline{CS0}$, $\overline{SCK0}$, $\overline{SCK1}$, $\overline{EC0}$, $\overline{EC1}$, RMC, \overline{NMI} , INT0, INT1, INT2, INT3.}^{*4) Specifies only during external clock input.}

Electrical Characteristics**DC Characteristics**

(Ta = -20 to +75°C, Vss = 0V reference)

Item	Symbol	Pins	Conditions	Min.	Typ.	Max.	Unit
High level output current	VOH	PA to PD, PE4, PE5, PF to PI	VDD = 4.5V, IOH = -0.5mA	4.0			V
			VDD = 4.5V, IOH = -1.2mA	3.5			V
Low level output current	VOL	VDD = 4.5V, IOL = 1.8mA				0.4	V
			VDD = 4.5V, IOL = 3.6mA			0.6	V
		PC	VDD = 4.5V, IOL = 12.0mA			1.5	V
Input current	I _{IEH}	EXTAL	VDD = 5.5V, VIH = 5.5V	0.5		40	μA
	I _{ILE}		VDD = 5.5V, VIL = 0.4V	-0.5		-40	μA
	I _{IHT}	TEX	VDD = 5.5V, VIL = 5.5V	0.1		10	μA
	I _{ILT}			-0.1		-10	μA
	I _{ILR}	RST ^{*1}	VDD = 5.5V, VIL = 0.4V	-1.5		-400	μA
	I _{IL}					-2.0	mA
		PA to PD ^{*2} , PF to PI ^{*2}	VDD = 4.5V, VIL = 4.0V	-10			μA
I/O leakage current	I _{Iz}	PE0 to PE3, RST ^{*1}	VDD = 5.5V, VI = 0, 5.5V			±10	μA
Power supply current ^{*3}	I _{DD1}	VDD	High-speed mode operation (1/2 frequency dividing clock)		32	52	mA
	I _{DD2}		VDD = 5.5V, 20MHz crystal oscillation (C ₁ = C ₂ = 15pF)				
	I _{DDS1}		VDD = 3V, 32kHz crystal oscillation (C ₁ = C ₂ = 47pF)		38	100	μA
	I _{DDS2}	VDD	SLEEP mode		1.4	10	mA
	I _{DDS3}		VDD = 5.5V, 20MHz crystal oscillation (C ₁ = C ₂ = 15pF)				
		VDD	VDD = 3V, 32kHz crystal oscillation (C ₁ = C ₂ = 47pF)		9	30	μA
			STOP mode		10	μA	
Input capacity	C _{IN}	PA, PB0 to PB6, PC, PD, PE0 to PE3, PF to PI, EXTAL, XTAL, TEX, TX, RST	Clock 1MHz 0V for all pins excluding measured pins				
					10	20	pF

*1) RST specifies the input current when pull-up resistance has been selected; leakage current when no resistance has been selected.

*2) PA to PD, and PF to PI pins specify the input current when pull-up resistance has been selected; leakage current when no resistance has been selected. (Excludes output PB7)

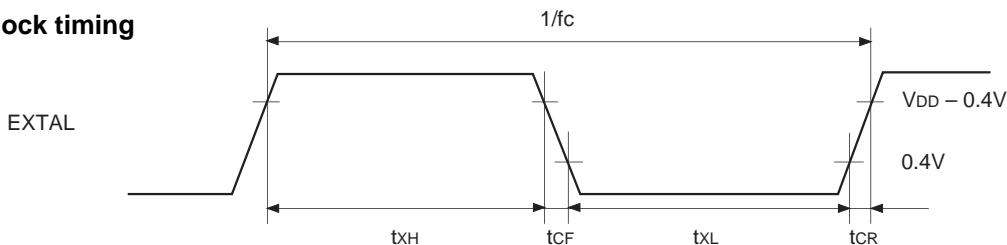
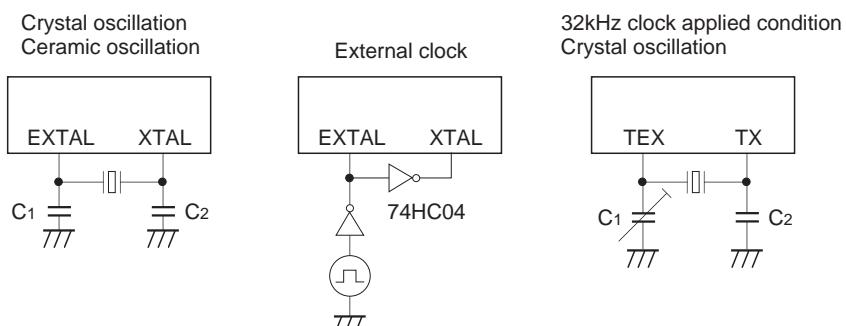
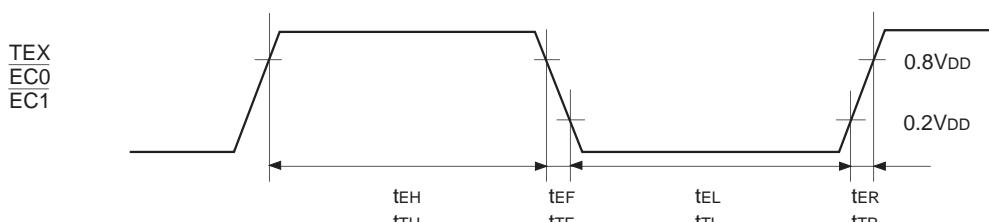
*3) When all pins are open.

AC Characteristics**(1) Clock timing**(Ta = -20 to +75°C, V_{DD} = 4.5 to 5.5V, V_{SS} = 0V reference)

Item	Symbol	Pin	Conditions	Min.	Typ.	Max.	Unit
System clock frequency	fc	XTAL EXTAL	Fig. 1, Fig. 2	1		20	MHz
System clock input pulse width	t _{XL} , t _{XH}	EXTAL	Fig. 1, Fig. 2 External clock drive	23.0			ns
System clock input rise time, fall time	t _{CR} , t _{CF}	EXTAL	Fig. 1, Fig. 2 External clock drive			200	ns
Event count input clock pulse width	t _{EH} , t _{EL}	EC0 EC1	Fig. 3	tsys + 50 ^{*1}			ns
Event count input clock rise time, fall time	t _{ER} , t _{EF}	EC0 EC1	Fig. 3			20	ms
System clock frequency	fc	TEX TX	V _{DD} = 2.7 to 5.5V Fig. 2 (32kHz clock applied condition)		32.768		kHz
Event count input clock input pulse width	t _{TL} , t _{TH}	TEX	Fig. 3	10			μs
Event count input clock rise time, fall time	t _{TR} , t _{TF}	TEX	Fig. 3			20	ms

*1) tsys indicates the three values below according to the upper two bits (CPU clock selected) of the control clock register (address: 00FEH).

tsys (ns) = 2000/fc (upper two bits = "00"), 4000/fc (upper two bits = "01"), 16000/fc (upper two bits = "11")

Fig. 1. Clock timing**Fig. 2. Clock applied conditions****Fig. 3. Event count clock timing**

(2) Serial transfer (CH0)

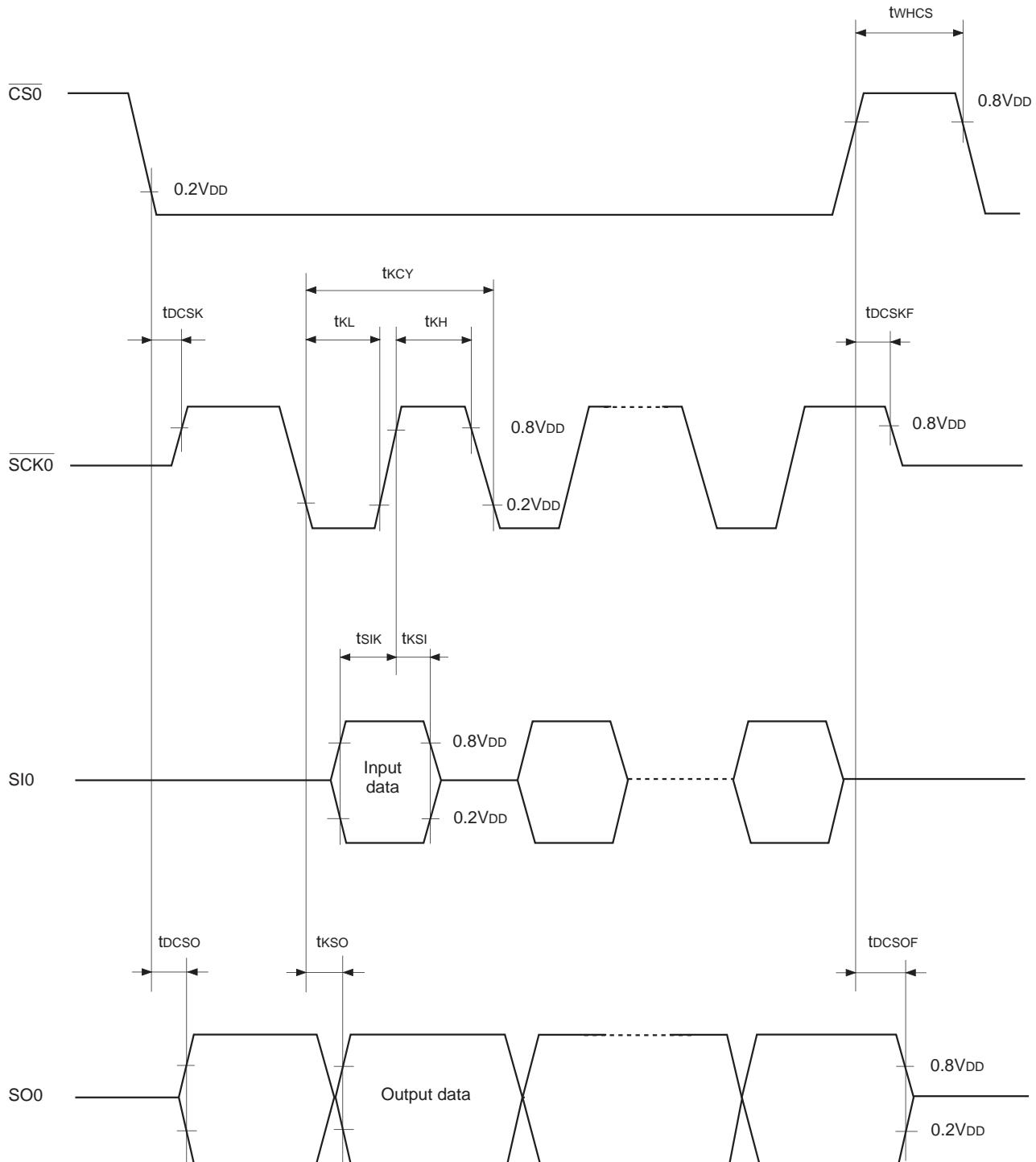
(Ta = -20 to +75°C, V_{DD} = 4.5 to 5.5V, V_{ss} reference)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
CS0 ↓ → SCK0 delay time	t _{bcsk}	SCK0	Chip select transfer mode (SCK0 = output mode)		t _{sys} + 200	ns
CS0 ↑ → SCK0 float delay time	t _{dcskf}	SCK0	Chip select transfer mode (SCK0 = output mode)		t _{sys} + 200	ns
CS0 ↓ → SO0 delay time	t _{dcso}	SO0	Chip select transfer mode		t _{sys} + 200	ns
CS0 ↑ → SO0 float delay time	t _{dcsof}	SO0	Chip select transfer mode		t _{sys} + 200	ns
CS0 High level width	t _{whcs}	CS0	Chip select transfer mode	t _{sys} + 200		ns
SCK0 cycle time	t _{kcy}	SCK0	Input mode	2t _{sys} + 200		ns
			Output mode	16000/fc		ns
SCK0 High, Low level width	t _{kh} t _{kl}	SCK0	Input mode	t _{sys} + 100		ns
			Output mode	8000/fc – 50		ns
SI0 input set-up time (for SCK0 ↑)	t _{siik}	SI0	SCK0 input mode	100		ns
			SCK0 output mode	200		ns
SI0 input hold time (for SCK0 ↑)	t _{ksi}	SI0	SCK0 input mode	t _{sys} + 200		ns
			SCK0 output mode	100		ns
SCK0 ↓ → SO0 delay time	t _{ks0}	SO0	SCK0 input mode		t _{sys} +200	ns
			SCK0 output mode		100	ns

Note 1) t_{sys} indicates the three values below according to the upper two bits (CPU clock selected) of the control clock register (address: 00FEH).

t_{sys} (ns) = 2000/fc (upper two bits = "00"), 4000/fc (upper two bits = "01"), 16000/fc (upper two bits = "11")

Note 2) The load condition for the SCK0 output mode, SO0 output delay time is 50pF + 1TTL.

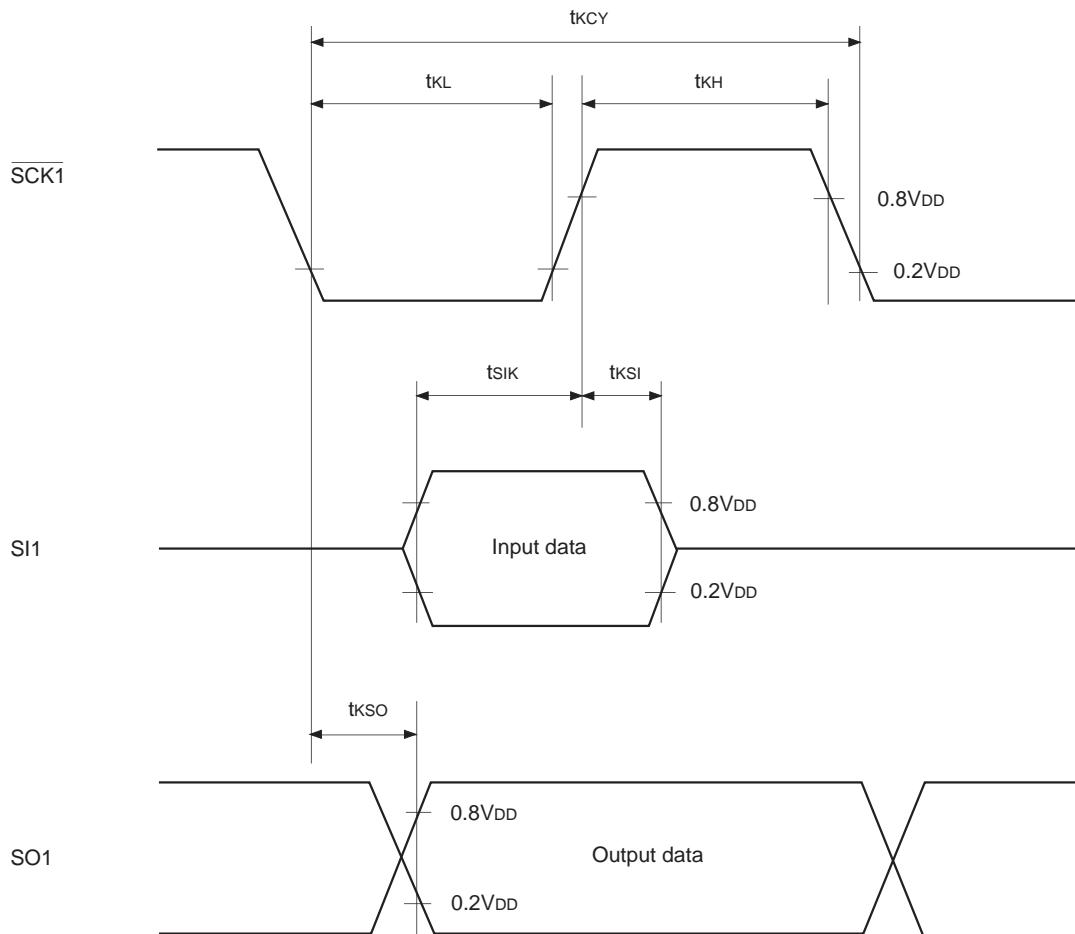
Fig. 4. Serial transfer CH0 timing

Serial transfer (CH1)

(Ta = -20 to +75°C, VDD = 4.5 to 5.5V, Vss = 0V reference)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
SCK1 cycle time	tkCY	SCK1	Input mode	1000		ns
			Output mode	16000/fc		ns
SCK1 High, Low level width	tKH tKL	SCK1	Input mode	400		ns
			Output mode	8000/fc – 50		ns
SI1 input set-up time (for SCK1 ↑)	tsIK	SI1	SCK1 input mode	100		ns
			SCK1 output mode	200		ns
SI1 input hold time (for SCK1 ↑)	tksi	SI1	SCK1 input mode	200		ns
			SCK1 output mode	100		ns
SCK1 ↓ → SO1 delay time	tkso	SO1	SCK1 input mode		200	ns
			SCK1 output mode		100	ns

Note) The load condition for the SCK1 output mode, SO1 output delay time is 50pF + 1TTL.

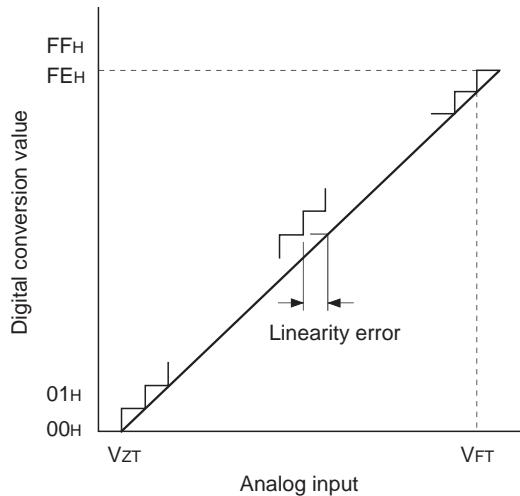
Fig. 5. Serial transfer CH1 timing

(3) A/D converter characteristics

(Ta = -20 to +75°C, VDD = 4.5 to 5.5V, AVREF = 4.0 to VDD, Vss = AVss = 0V reference)

Item	Symbol	Pin	Condition	Min.	Typ.	Max.	Unit
Resolution						8	Bits
Linearity error						±5	LSB
Zero transition voltage	VZT ^{*1}		Ta = 25°C VDD = AVREF = 5.0V Vss = AVss = 0V	-10	10	110	mV
Full-scale transition voltage	VFT ^{*2}			4870	4970	5070	mV
Conversion time	tCONV			160/fADC ^{*3}			μs
Sampling time	tSAMP			12/fADC ^{*3}			μs
Reference input voltage	VREF	AVREF		VDD - 0.5		VDD	V
Analog input voltage	VIAN	AN0 to AN7		0		AVREF	V
AVREF current	IREF	AVREF	Operation mode		0.6	1.0	mA
	IREFS		SLEEP mode STOP mode 32kHz operation mode			10	μA

Fig. 6. Definition of A/D converter terms



*1) VZT : Value at which the digital transfer value changes from 00H to 01H and vice versa.

*2) VFT : Value at which the digital transfer value changes from FEH to FFH and vice versa.

*3) fADC indicates the values below due to the contents of bit 6 (CKS) of the A/D control register (ADC: 00F9H) and bits 7 (PCK1) and 6 (PCK0) of the clock control register (CLC: 00FEH).

CKS PCK1, 0	0 (ϕ/2 selection)	1 (ϕ selection)
00 (ϕ = fEX/2)	fADC = fc/2	fADC = fc
01 (ϕ = fEX/4)	fADC = fc/4	fADC = fc/2
11 (ϕ = fEX/16)	fADC = fc/16	fADC = fc/8

(4) Interruption, reset input (Ta = -20 to +75°C, V_{DD} = 4.5 to 5.5V, V_{SS} = 0V reference)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
External interruption High, Low level width	t _{IH} t _{IL}	INT0 INT1 INT2 INT3 NMI		1		μs
Reset input Low level width	t _{RSL}	$\overline{\text{RST}}$		32/fc		μs

Fig 7. Interruption input timing

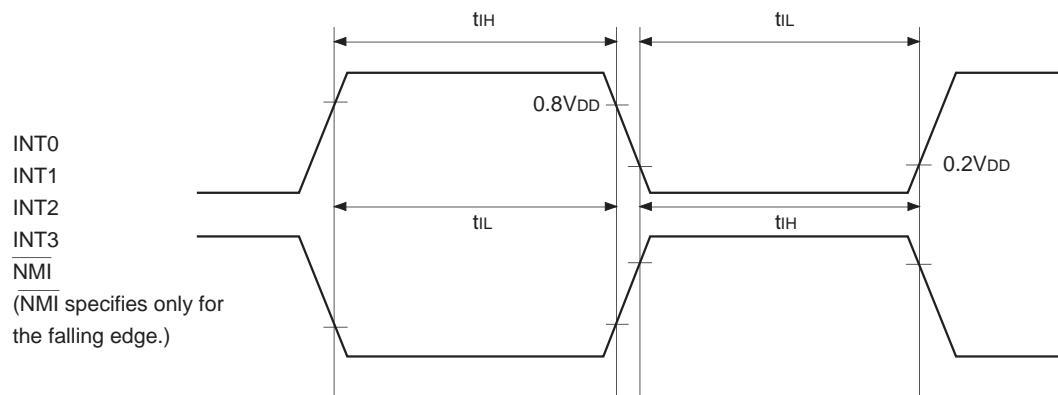
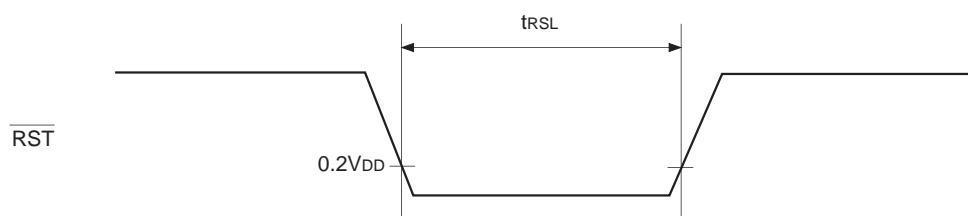


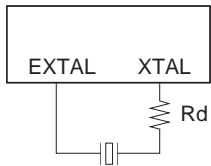
Fig. 8. $\overline{\text{RST}}$ input timing



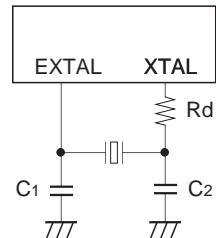
Appendix

Fig. 9. Recommended oscillation circuit

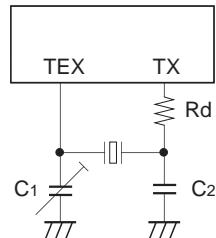
(i) Main clock



(ii) Main clock



(iii) Sub clock

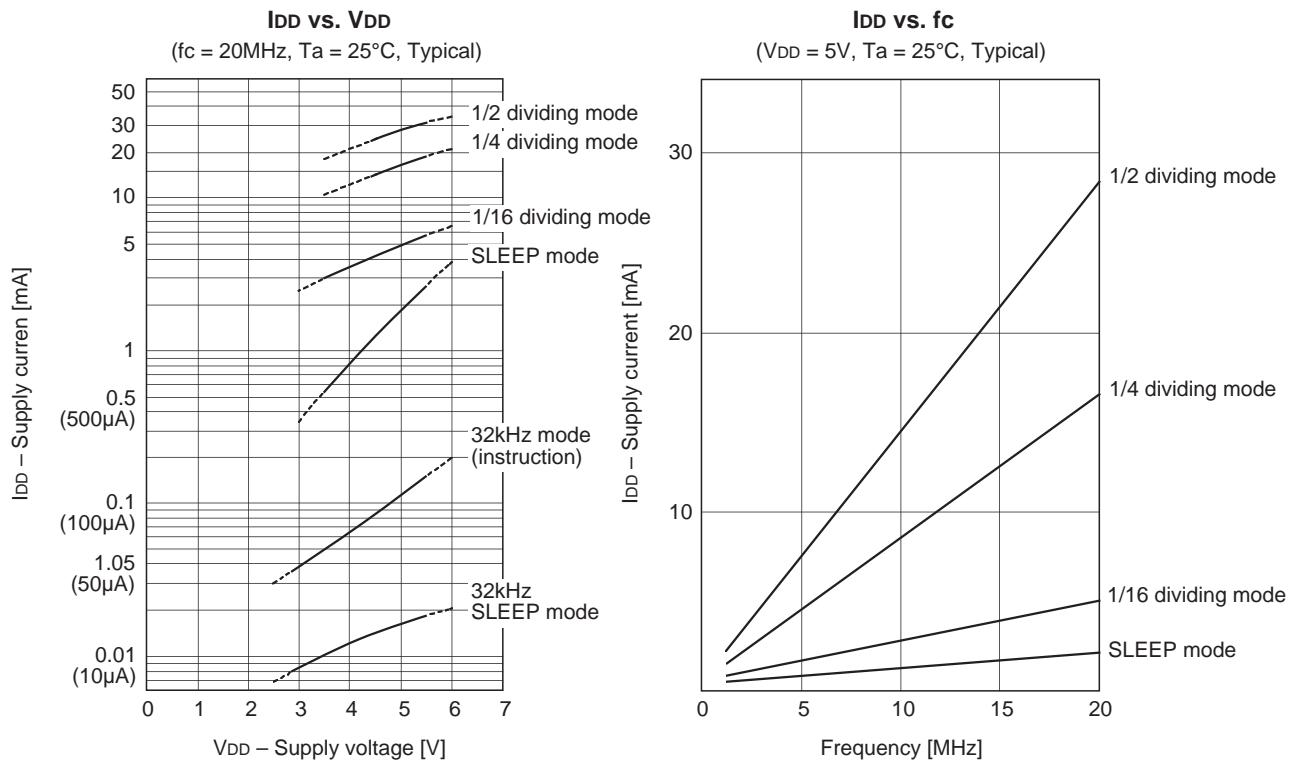


Products List

Manufacturer	Model	fc (MHz)	C1 (pF)	C2 (pF)	Rd (Ω)	Circuit example
MURATA MFG CO., LTD.	CSA16.00MXZ072	16.00	0	0	0	(i)
	CSA20.00MXZ046	20.00				
RIVER ELETEC CO., LTD.	HC-49/U03	16.00	8	8	0	(ii)
		20.00	6	6		
KINSEKI LTD.	P3	32.768kHz	50	22	1M	(iii)

Mask option table

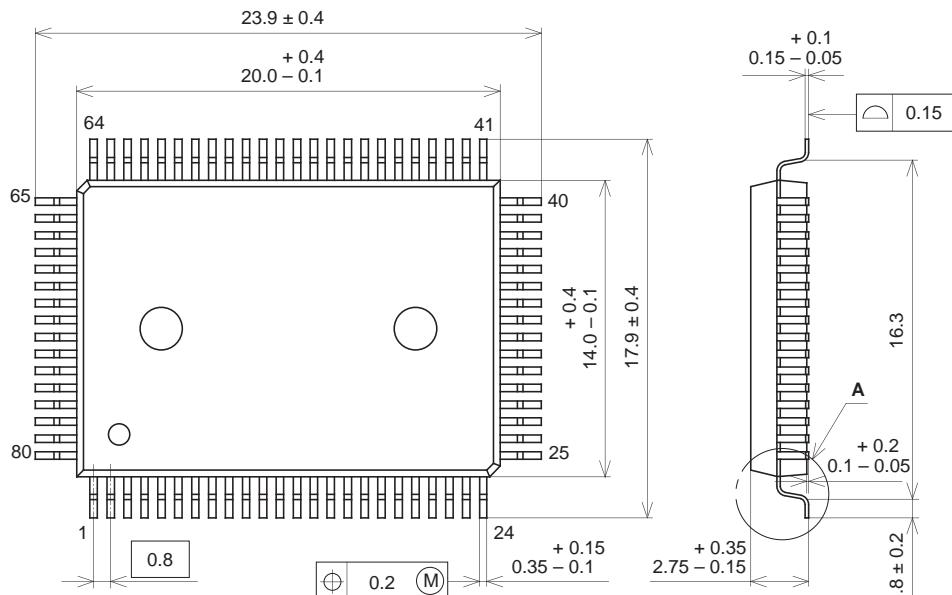
Item	Content	
Reset pin pull-up resistance	Non-existent	Existent

Example of Representative Characteristics

Package Outline

Unit: mm

80PIN QFP (PLASTIC)



DETAIL A

PACKAGE STRUCTURE

SONY CODE	QFP-80P-L01
EIAJ CODE	QFP080-P-1420
JEDEC CODE	-----

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42/COPPER ALLOY
PACKAGE MASS	1.6g